

Material Declaration Report



Package Type:	EP-SOP8
Pericom Package Code:	WA8(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	79.950
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	7-22
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	Nov. 14,2014

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	47.819	J	Epoxy Resin A	Trade Secret	7.50	3.58643
			Epoxy Resin B	29690-82-2	0.75	0.35864
			Phenol Resin	Trade Secret	3.00	1.43457
			Silica(Amorphous) A	60676-86-0	85.00	40.64615
			Silica(Amorphous) B	7631-86-9	3.00	1.43457
			Carbon Black	1333-86-4	0.75	0.35864
LEAD FRAME	30.193		Cu	7440-50-8	97.37	29.39953
			Fe	7439-89-6	2.350	0.70954
			Pb	7439-92-1	0.025	0.00755
			P	7723-14-0	0.0825	0.02491
			Zn	7440-66-6	0.125	0.03774
			Ag	7740-22-4	0.045	0.01359
TERMINATION PLATING	0.7500		Tin	7440-31-5	99.90	0.74925
			Others	NA	0.10	0.00075
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.325		Silver	7440-22-4	86.50	0.28113
			Butyrolactone 4-	96-48-0	3.00	0.00975
			Bisphenol-F epichlorhydrin resin	9003-36-5	7.50	0.02438
			2,6-Diglycidyl phenyl allyl ether oligomer	unassigned	3.00	0.00975
GOLD WIRE	0.513		Au	7440-57-5	99.99	0.51295
			Others	Proprietary	0.01	0.00005

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<25	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<60	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
		<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
		O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.